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CH.	Juno	tion-to-ambi	isio ent	thermal	resistan	ce v	alues increas		<b>2)</b> 58 is no	w 1	09.1, DE	3 was 70 is now 12	Page 2.7,
_	N wa	as 69 is now Texas Instrumei		6, NS w	as 60 is	now	113.4, PW w	as 83 is now			SN	<b>54HCT373, SN74HC</b> RCH 1984 – REVISED JULY	T373
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#### SN54HCT373, SN74HCT373

SCLS009G - MARCH 1984 - REVISED JULY 2022

## Changes from Revision F (December 2021) to Revision G (July 2022)

Removed DB package.....



SN54HC540, SN74HC540

SCLS007F - MARCH 1984 - REVISED JULY 2022

#### Changes from Revision E (January 2022) to Revision F (July 2022)

Junction-to-ambient thermal resistance values increased. DW was 58 is now 109.1, N was 69 is now 84.6, NS was 60 is now 113.4, PW was 83 is now 131.8......4

The datasheet number will be changing.

The database number will be endinging.		
Device Family	Change From:	Change To:
SNx4HCT573	SCLS176F	SCLS176G
SNx4HC563	SCLS145D	SCLS145E
SNx4HCT273	SCLS068F	SCLS068G
SNx4HCT373	SCLS009E	SCLS009G
SNx4HC540	SCLS007E	SCLS007F

These changes may be reviewed at the datasheet links provided.

https://www.ti.com/product/SN54HCT573

https://www.ti.com/product/SN54HC563

https://www.ti.com/product/SN54HCT273

https://www.ti.com/product/SN54HCT373

https://www.ti.com/product/SN54HC540

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## **Reason for Change:**

To accurately reflect device characteristics.

### Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. There are no changes to the actual device for this document update.

### **Changes to product identification resulting from this notification:**

None.

### **Product Affected:**

SN74HC540DW	SN74HC563DW	SN74HCT273PW	SN74HCT373PWT	
SN74HC540DWE4	SN74HC563DWR	SN74HCT273PWR	SN74HCT573DBR	
SN74HC540DWG4	SN74HC563N	SN74HCT273PWT	SN74HCT573DBRG4	
SN74HC540DWR	SN74HC563NS	SN74HCT373DW	SN74HCT573DW	
SN74HC540N	SN74HCT273DBR	SN74HCT373DWR	SN74HCT573DWR	
SN74HC540NS	SN74HCT273DW	SN74HCT373DWRE4	SN74HCT573DWRG4	
SN74HC540NSR	SN74HCT273DWR	SN74HCT373N	SN74HCT573N	
SN74HC540PW	SN74HCT273DWRG4	SN74HCT373NE4	SN74HCT573NS	

SN74HC540PWR	SN74HCT273N	SN74HCT373NSR	SN74HCT573NSR
SN74HC540PWRE4	SN74HCT273NS	SN74HCT373PW	SN74HCT573PW
SN74HC540PWT	SN74HCT273NSR	SN74HCT373PWR	SN74HCT573PWR

For questions regarding this notice, e-mails can be sent to the contact shown below or your local Field Sales Representative.

Location	E-Mail				
WW PCN Team	PCN www admin team@list.ti.com				

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Notification# 20220714000.0